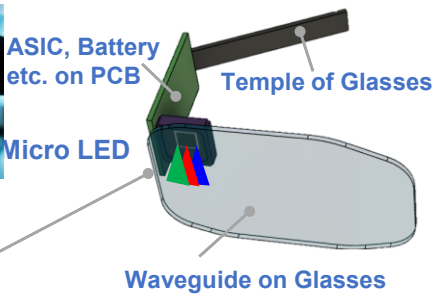
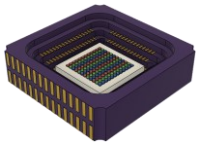
# Ceramic Packaging Solutions for AR/VR/MR Applications

## AR GLASSES



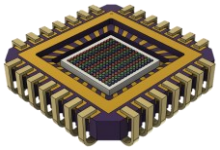



**QFN/LCC Package**



Ceramic Package w/ Side Pads (Optional)

**QFJ Package**



J-shaped Metal Leads

**Window Lid**



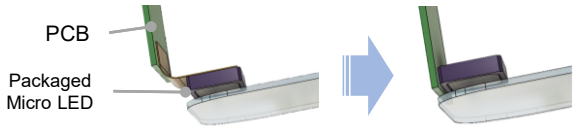
Epoxy Pre-attached

➢ **Miniaturization Advancements:**
- Component integration on bottom cavity
- Removal of flex cable with side-surface mountable structure



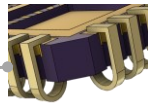
Bottom Cavity

**Flex Cable Connection** **Directly Bonding on PCB**



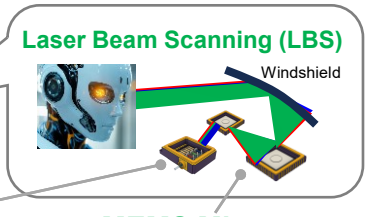

➢ **Metal Leaded Version for Greater Reliability with Minimized Assembly Area**

J-shaped Metal Leads, overhung on ceramic body for good soldering fillet with PCB

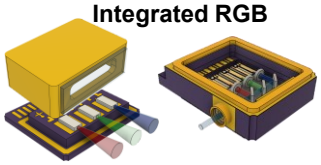


## AR Heads-Up Display

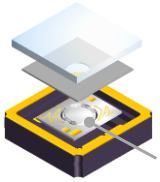





**Package & Lid for Integrated RGB**



**LCC Package**



MEMS Mirror

**Window Lid**



➢ **Miniaturization Advancements:**
- Flexible design and robustness for optical axis control

➢ **Performance Enhancements:**
- Optimal thermal path with integrated heat sink
- AR coated window

➢ **Flexible Design for Various Laser Types**

Integrated RGB Package



TO56 Package



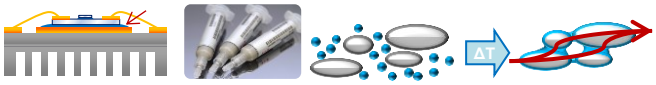
SMD Package



Thin Film Carrier

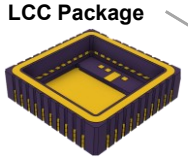


➢ **High Reliability Through Sintering Mechanism**
- High-temperature-resistant bonding
- Efficiently dissipates heat generated by device



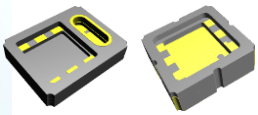

## Related Sensors / Devices

**Inertial Sensor**
**LCC Package**

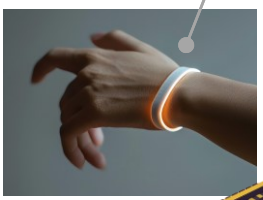




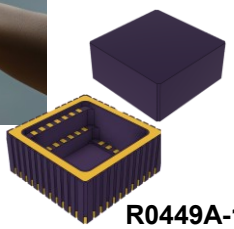
**ToF Sensor**
**LCC Package**



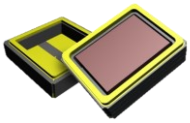
**Quantum Magnetic Sensor**
**for NV*-Center**
*Nitrogen-Vacancy



**Deep Cavity LCC Package & Lid**



**Battery**
**SMD Package**
**for Solid State Battery**



**Si Microphone**
**SMD Package & Lid**

Through Hole for Mic



R0449A-1

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